Complementary 40 V, 6.0 A, Low V_{CE(sat)} Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating		Symbol	Max	Unit
Collector-Emitter Voltage	NPN PNP	V _{CEO}	40 -40	Vdc
Collector-Base Voltage	NPN PNP	V _{CBO}	40 -40	Vdc
Emitter-Base Voltage	NPN PNP	V _{EBO}	6.0 -7.0	Vdc
Collector Current – Continuous	NPN PNP	I _C	3.0 -3.0	Α
Collector Current - Peak	NPN PNP	I _{CM}	6.0 -6.0	А
Electrostatic Discharge		ESD	HBM Class 3B MM Class C	

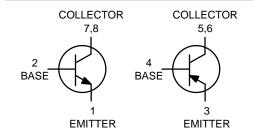
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



ON Semiconductor®

www.onsemi.com

40 VOLTS, 6.0 AMPS COMPLEMENTARY LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 80 m Ω





STYLE 16 DEVICE MARKING



C40302 = Specific Device Code

= Assembly Location = Year

WW = Work Week

= Pb-Free Package(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40302PDR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NSV40302PDR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
SINGLE HEATED			
Total Device Dissipation (Note 1)	P _D	576	mW
T _A = 25°C Derate above 25°C		4.6	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ hetaJA}$	217	°C/W
Total Device Dissipation (Note 2)	P _D	676	mW
T _A = 25°C Derate above 25°C		5.4	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	185	°C/W
DUAL HEATED (Note 3)			
Total Device Dissipation (Note 1)	P _D	653	mW
T _A = 25°C Derate above 25°C		5.2	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ hetaJA}$	191	°C/W
Total Device Dissipation (Note 2)	P _D	783	mW
T _A = 25°C Derate above 25°C		6.3	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	160	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

FR-4 @ 10 mm², 1 oz. copper traces, still air.
 FR-4 @ 100 mm², 1 oz. copper traces, still air.
 Dual heated values assume total power is the sum of two equally powered devices.

NPN ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	40	_	_	Vdc
Collector – Base Breakdown Voltage (I _C = 0.1 mAdc, I _E = 0)	V _{(BR)CBO}	40	-	-	Vdc
Emitter – Base Breakdown Voltage (I _E = 0.1 mAdc, I _C = 0)	V _{(BR)EBO}	6.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = 40 Vdc, I _E = 0)	Ісво	-	_	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	_	0.1	μAdc
ON CHARACTERISTICS			•		•
DC Current Gain (Note 5) ($I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$) ($I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$)	h _{FE}	200 200 180 180	400 350 340 320	- - -	
Collector – Emitter Saturation Voltage (Note 5) $ \begin{aligned} &(I_C = 0.1 \text{ A}, I_B = 0.010 \text{ A}) \\ &(I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}) \\ &(I_C = 1.0 \text{ A}, I_B = 0.010 \text{ A}) \\ &(I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}) \end{aligned} $	V _{CE} (sat)	- - - -	0.008 0.044 0.080 0.082	0.011 0.060 0.115 0.115	V
Base – Emitter Saturation Voltage (Note 5) (I _C = 1.0 A, I _B = 0.01 A)	V _{BE(sat)}	-	0.780	0.900	V
Base – Emitter Turn–on Voltage (Note 5) (I _C = 0.1 A, V _{CE} = 2.0 V)	V _{BE(on)}	-	0.650	0.750	V
Cutoff Frequency (I _C = 100 mA, V _{CE} = 5.0 V, f = 100 MHz)	f _T	100	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	_	320	450	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	_	40	50	pF
SWITCHING CHARACTERISTICS	•				
Delay (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _d	-	-	100	ns
Rise ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	-	-	100	ns
Storage ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _s	-	-	780	ns
Fall (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	_	_	110	ns

4. Pulsed Condition: Pulse Width = $300 \,\mu\text{sec}$, Duty Cycle $\leq 2\%$. Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PNP ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Min	Тур	Max	Unit
V _{(BR)CEO}	-40	_	_	Vdc
V _{(BR)CBO}	-40	-	_	Vdc
V _{(BR)EBO}	-7.0	-	-	Vdc
Ісво	-	-	-0.1	μAdc
I _{EBO}	-	_	-0.1	μAdc
	•	•	•	•
h _{FE}	250 220 180 150	380 340 300 230	- - - -	
V _{CE(sat)}	- - - -	-0.013 -0.075 -0.130 -0.135	-0.017 -0.095 -0.170 -0.170	V
V _{BE(sat)}	-	-0.780	-0.900	V
V _{BE(on)}	-	-0.660	-0.750	V
f _T	100	-	-	MHz
Cibo	-	250	300	pF
Cobo	-	50	65	pF
t _d	_	_	60	ns
t _r	-	-	120	ns
t _s	_	_	400	ns
t _f	_	-	130	ns
	V(BR)CEO V(BR)CBO V(BR)EBO ICBO IEBO VCE(sat) VBE(sat) VBE(on) f _T Cibo Cobo t _d t _r t _s	V(BR)CEO	V(BR)CEO -40 - V(BR)CBO -40 - V(BR)EBO -7.0 - ICBO - - IEBO - - VCE(sat) - - VCE(sat) - - VBE(sat) - - VBE(sat) - - VBE(sat) - - VBE(sat) - - Cobo - - Tr Tr Tr Tr Tr Tr Tr Tr Tr Tr <td>V(BR)CEO -40 - - V(BR)CBO -40 - - V(BR)EBO -7.0 - - ICBO - - -0.1 IEBO - - -0.1 IBO 380 - - 180 300 - - 180 300 - - 150 230 - - VCE(sat) - -0.013 -0.017 - - -0.130 -0.170 - -0.130 -0.170 VBE(sat) - -0.780 -0.900 - VBE(on) - -0.660 -0.750 fT 100 - - - Cobo - 50 65 td - - 60 - tg - - - 400</td>	V(BR)CEO -40 - - V(BR)CBO -40 - - V(BR)EBO -7.0 - - ICBO - - -0.1 IEBO - - -0.1 IBO 380 - - 180 300 - - 180 300 - - 150 230 - - VCE(sat) - -0.013 -0.017 - - -0.130 -0.170 - -0.130 -0.170 VBE(sat) - -0.780 -0.900 - VBE(on) - -0.660 -0.750 fT 100 - - - Cobo - 50 65 td - - 60 - tg - - - 400

Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.

NPN TYPICAL CHARACTERISTICS

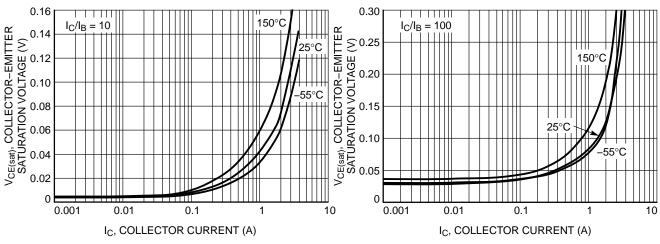


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

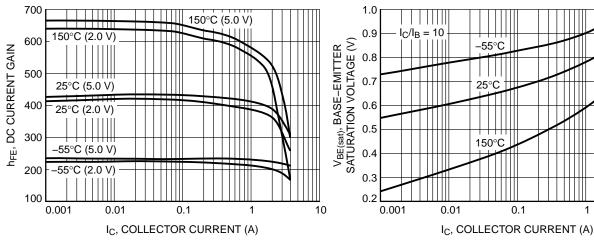


Figure 3. DC Current Gain vs. Collector Current

Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

10

0.1

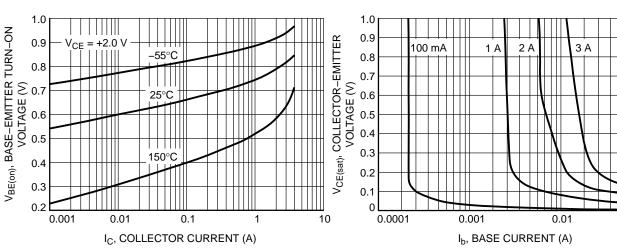


Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

Figure 6. Saturation Region

NPN TYPICAL CHARACTERISTICS

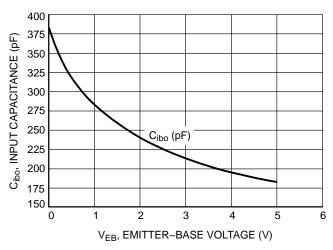


Figure 7. Input Capacitance

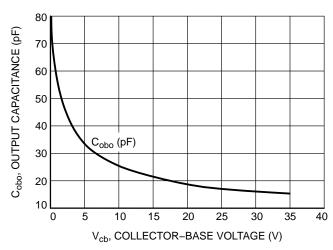


Figure 8. Output Capacitance

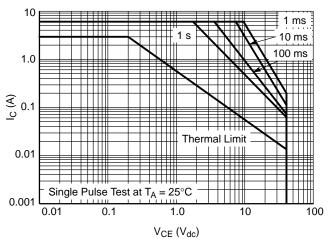


Figure 9. Safe Operating Area

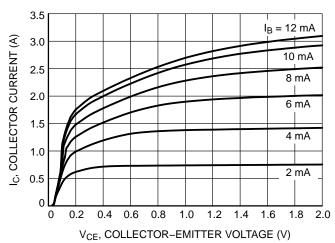


Figure 10. Collector Current as a Function of Collector Emitter Voltage

PNP TYPICAL CHARACTERISTICS

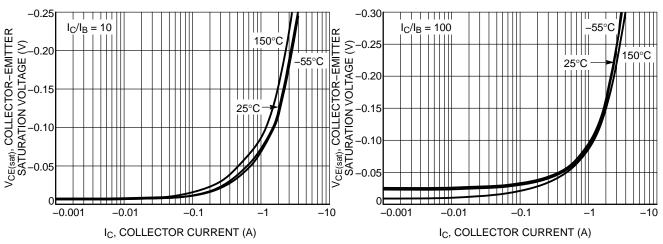


Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

Figure 12. Collector Emitter Saturation Voltage vs. Collector Current

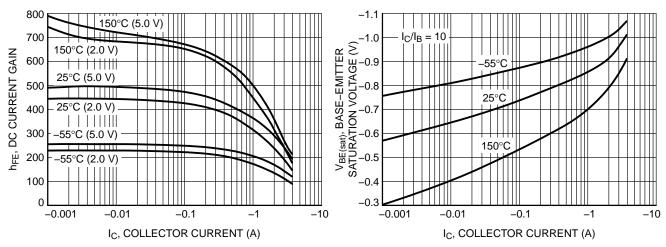


Figure 13. DC Current Gain vs. Collector Current

Figure 14. Base Emitter Saturation Voltage vs.
Collector Current

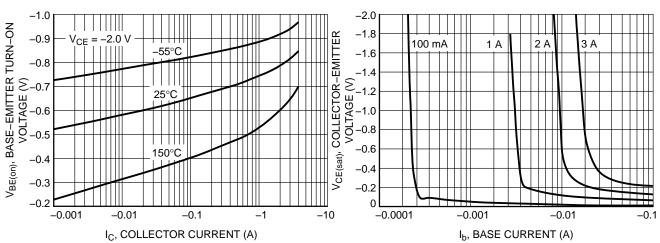
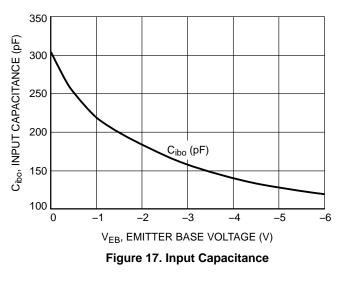


Figure 15. Base Emitter Turn-On Voltage vs. Collector Current

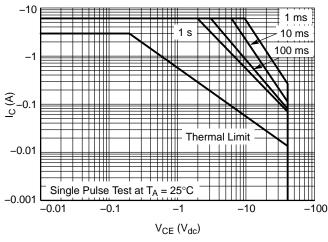
Figure 16. Saturation Region

PNP TYPICAL CHARACTERISTICS



100 C_{obo}, OUTPUT CAPACITANCE (pF) 90 80 70 60 50 C_{obo} (pF) 40 30 0 -20 -25 -30 -5 -15 -35 -40 V_{cb}, COLLECTOR BASE VOLTAGE (V)

Figure 18. Output Capacitance



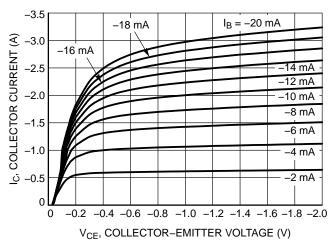


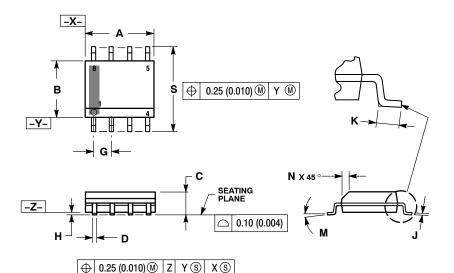
Figure 19. Safe Operating Area

Figure 20. Output Capacitance



SOIC-8 NB CASE 751-07 **ISSUE AK**

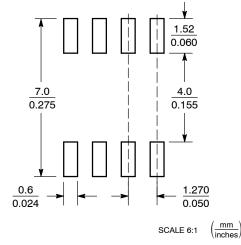
DATE 16 FEB 2011



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
Н	0.10	0.25	0.004	0.010
7	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

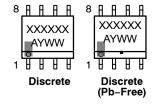
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location = Wafer Lot

= Year = Work Week

= Pb-Free Package



XXXXXX = Specific Device Code = Assembly Location Α

= Year ww

= Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42564B	Electronic versions are uncontrolled except when accessed directly from the Document Report Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC-8 NB		PAGE 1 OF 2	

ON Semiconductor and un are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

SOIC-8 NB CASE 751-07 ISSUE AK

DATE 16 FEB 2011

STYLE 3: PIN 1. DRAIN, PIE #1 CTOR, #1 CTOR, #2 CTOR, #1 CTOR, #2 CTOR, #1	2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #1 Vd STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN 8. TYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #1
E PIN 1. INPUT 2. EXTERNAL BY 3. THIRD STAGE 4. GROUND E 5. DRAIN 6. GATE 3 7. SECOND STAGE 8. FIRST STAGE STYLE 11: ID PIN 1. SOURCE 1 2. GATE 1 T 3. SOURCE 2 ID 4. GATE 2 ID 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 ID 8. DRAIN 1 ID	PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 Vd 8. COLLECTOR, #1 STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN 8. TYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2
ID PIN 1. SOURCE 1 2. GATE 1 T 3. SOURCE 2 ID 4. GATE 2 ID 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 ID 8. DRAIN 1 STYLE 15: RCE PIN 1. ANODE 1 E 2. ANODE 1 RCE 3. ANODE 1	PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2
STYLE 15: RCE PIN 1. ANODE 1 E 2. ANODE 1 RCE 3. ANODE 1	PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2
N 7. CATHODE, CON N 8. CATHODE, CON	MMON 5. COLLECTOR, DIE #2 MMON 6. COLLECTOR, DIE #2 MMON 7. COLLECTOR, DIE #1 MMON 8. COLLECTOR, DIE #1
STYLE 19: PIN 1. SOURCE 1 E 2. GATE 1 E 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 DE 7. DRAIN 1 DE 8. MIRROR 1	STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 23: E1 PIN 1. LINE 1 IN DN CATHODE/VCC 2. COMMON ANC DN CATHODE/VCC 3. COMMON ANC E3 4. LINE 2 IN DN ANODE/GND 5. LINE 2 OUT E4 6. COMMON ANC E5 7. COMMON ANC DN ANODE/GND 8. LINE 1 OUT	ODE/GND 2. EMITTER ODE/GND 3. COLLECTOR/ANODE
STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V MON 6. VBULK 7. VBULK 8. VIN
1 1	
;	STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ E 5. SOURCE E 6. SOURCE E 7. SOURCE 8. DRAIN

DOCUMENT NUMBER:	98ASB42564B	Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC-8 NB		PAGE 2 OF 2	

ON Semiconductor and IN are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative